

1	58817	resist WITH pattern	USPAT; EPO; JPO; DERWENT; IBM_TDB
2	3394	(resist WITH pattern) SAME photolithography	USPAT; EPO; JPO; DERWENT; IBM_TDB
3	4817	(resist WITH pattern) SAME photolithograph\$?	USPAT; EPO; JPO; DERWENT; IBM_TDB
4	6	((resist WITH pattern) SAME photolithograph\$?) SAME polariz\$?	USPAT; EPO; JPO; DERWENT; IBM_TDB
6	667	(mold\$? OR pressing) WITH photoresist	USPAT; EPO; JPO; DERWENT; IBM_TDB
7	128	((mold\$? OR pressing) WITH photoresist) SAME etching	USPAT; EPO; JPO; DERWENT; IBM_TDB
8	163000	emboss\$? OR photoresist	USPAT; EPO; JPO; DERWENT; IBM_TDB
9	181	emboss\$? WITH photoresist	USPAT; EPO; JPO; DERWENT; IBM_TDB
10	89	216/44[ccls]	USPAT; EPO; JPO; DERWENT;

L Number	Hits	Search Text <i>same</i> <i>: yield 80 hits, none relevant</i>	DB
16	0	(((mold OR mask\$?) WITH (wire-grid OR (wire ADJ1 grid))) SAME (photoresist OR resist)) AND heating	USPAT; EPO; JPO; DERWENT; IBM_TDB
14	2	((mold OR mask\$?) WITH (wire-grid OR (wire ADJ1 grid))) SAME (photoresist OR resist)	USPAT; EPO; JPO; DERWENT; IBM_TDB
13	43	(mold OR mask\$?) WITH (wire-grid OR (wire ADJ1 grid))	USPAT; EPO; JPO; DERWENT; IBM_TDB
-	1443	AR ADJ1 coat\$?	USPAT; EPO; JPO; DERWENT; IBM_TDB
-	13592	antireflect\$?	USPAT; EPO; JPO; DERWENT; IBM_TDB
-	16824	anti ADJ1 reflect\$?	USPAT; EPO; JPO; DERWENT; IBM_TDB
-	9	((AR ADJ1 coat\$?) OR antireflect\$? OR (anti ADJ1 reflect\$?)) WITH (wire-grid OR (wire ADJ1 grid))	USPAT; EPO; JPO; DERWENT; IBM_TDB